



## IGBT

High speed 5 FAST IGBT in TRENCHSTOP™ 5 technology

### IGP40N65F5, IGW40N65F5

650V IGBT high speed switching series fifth generation

Data sheet

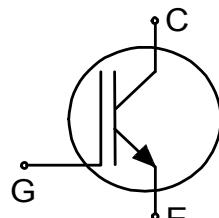
Industrial Power Control

## High speed 5 FAST IGBT in TRENCHSTOP™ 5 technology

### Features and Benefits:

High speed F5 technology offering

- Best-in-Class efficiency in hard switching and resonant topologies
- 650V breakdown voltage
- Low gate charge  $Q_G$
- Ideal fit with SiC Schottky Diode in boost converters
- Maximum junction temperature 175°C
- Qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models:  
<http://www.infineon.com/igbt/>



### Target Applications:

- Solar converters
- Uninterruptible power supplies
- Welding converters
- Mid to high range switching frequency converters

### Package pin definition:

- Pin 1 - gate
- Pin 2 & backside - collector
- Pin 3 - emitter



### Key Performance and Package Parameters

Type	$V_{CE}$	$I_C$	$V_{CEsat}, T_{vj}=25^\circ\text{C}$	$T_{vjmax}$	Marking	Package
IGP40N65F5	650V	40A	1.6V	175°C	G40EF5	PG-T0220-3
IGW40N65F5	650V	40A	1.6V	175°C	G40EF5	PG-T0247-3

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### Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25^\circ\text{C}$	$V_{CE}$	650	V
DC collector current, limited by $T_{vjmax}$ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	$I_C$	74.0 46.0	A
Pulsed collector current, $t_p$ limited by $T_{vjmax}$	$I_{Cpuls}$	120.0	A
Turn off safe operating area $V_{CE} \leq 650\text{V}$ , $T_{vj} \leq 175^\circ\text{C}$ , $t_p = 1\mu\text{s}$	-	120.0	A
Gate-emitter voltage Transient Gate-emitter voltage ( $t_p \leq 10\mu\text{s}$ , D < 0.010)	$V_{GE}$	$\pm 20$ $\pm 30$	V
Power dissipation $T_C = 25^\circ\text{C}$ Power dissipation $T_C = 100^\circ\text{C}$	$P_{tot}$	250.0 125.0	W
Operating junction temperature	$T_{vj}$	-40...+175	°C
Storage temperature	$T_{stg}$	-55...+150	°C
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s	PG-T0220-3 PG-T0247-3	260 260	°C
Mounting torque, M3 screw Maximum of mounting processes: 3	$M$	0.6	Nm

### Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction - case	$R_{th(j-c)}$		0.60	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$	PG-T0220-3 PG-T0247-3	62 40	K/W

### Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{V}$ , $I_C = 0.20\text{mA}$	650	-	-	V
Collector-emitter saturation voltage	$V_{CESat}$	$V_{GE} = 15.0\text{V}$ , $I_C = 40.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 125^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	-	1.60 1.80 1.90	2.10	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 0.40\text{mA}$ , $V_{CE} = V_{GE}$	3.2	4.0	4.8	V
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 650\text{V}$ , $V_{GE} = 0\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 175^\circ\text{C}$	-	-	40.0 2000.0	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0\text{V}$ , $V_{GE} = 20\text{V}$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE} = 20\text{V}$ , $I_C = 40.0\text{A}$	-	50.0	-	S

**Electrical Characteristic, at  $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified**

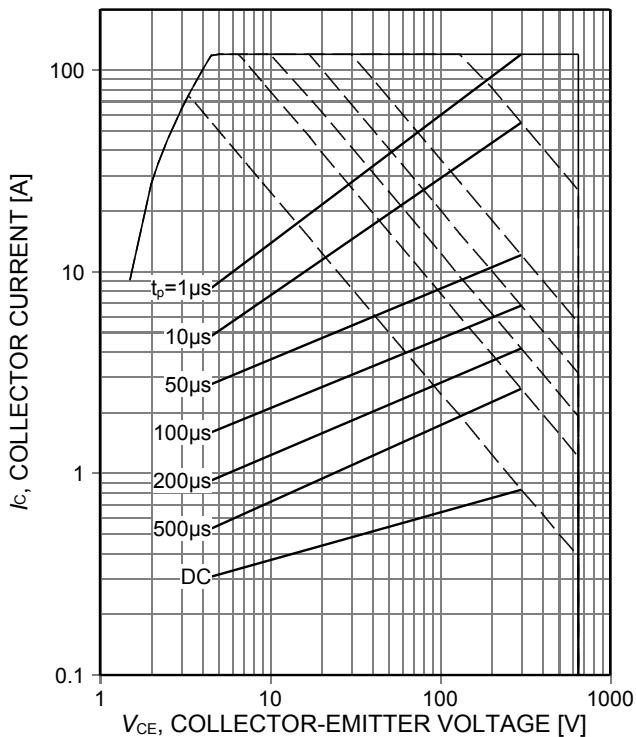
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	2500	-	pF
Output capacitance	$C_{oes}$		-	40	-	
Reverse transfer capacitance	$C_{res}$		-	9	-	
Gate charge	$Q_G$	$V_{CC} = 520\text{V}, I_C = 40.0\text{A}, V_{GE} = 15\text{V}$	-	95.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$	PG-T0220-3 PG-T0247-3	-	7.0 13.0	-	nH

**Switching Characteristic, Inductive Load**

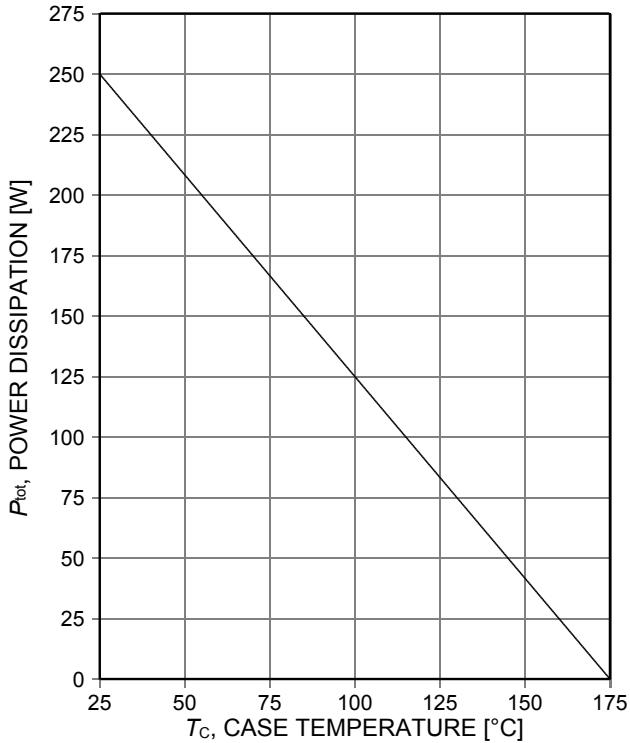
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic, at <math>T_{vj} = 25^\circ\text{C}</math></b>						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^\circ\text{C}, V_{CC} = 400\text{V}, I_C = 20.0\text{A}, V_{GE} = 0.0/15.0\text{V}, R_{G(on)} = 15.0\Omega, R_{G(off)} = 15.0\Omega, L_\sigma = 30\text{nH}, C_\sigma = 30\text{pF}$ $L_\sigma, C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	19	-	ns
Rise time	$t_r$		-	13	-	ns
Turn-off delay time	$t_{d(off)}$		-	160	-	ns
Fall time	$t_f$		-	16	-	ns
Turn-on energy	$E_{on}$		-	0.36	-	mJ
Turn-off energy	$E_{off}$		-	0.10	-	mJ
Total switching energy	$E_{ts}$		-	0.46	-	mJ
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^\circ\text{C}, V_{CC} = 400\text{V}, I_C = 5.0\text{A}, V_{GE} = 0.0/15.0\text{V}, R_{G(on)} = 15.0\Omega, R_{G(off)} = 15.0\Omega, L_\sigma = 30\text{nH}, C_\sigma = 30\text{pF}$ $L_\sigma, C_\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	20	-	ns
Rise time	$t_r$		-	4	-	ns
Turn-off delay time	$t_{d(off)}$		-	175	-	ns
Fall time	$t_f$		-	10	-	ns
Turn-on energy	$E_{on}$		-	0.07	-	mJ
Turn-off energy	$E_{off}$		-	0.03	-	mJ
Total switching energy	$E_{ts}$		-	0.10	-	mJ

**Switching Characteristic, Inductive Load**

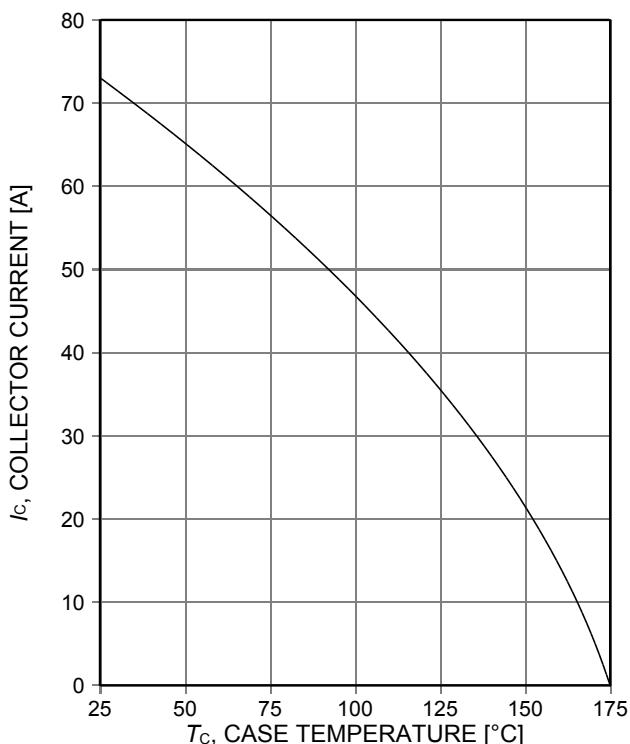
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic, at <math>T_{vj} = 150^\circ\text{C}</math></b>						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 150^\circ\text{C}$ , $V_{CC} = 400\text{V}$ , $I_C = 20.0\text{A}$ , $V_{GE} = 0.0/15.0\text{V}$ , $R_{G(on)} = 15.0\Omega$ , $R_{G(off)} = 15.0\Omega$ , $L\sigma = 30\text{nH}$ , $C\sigma = 30\text{pF}$ $L\sigma$ , $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	20	-	ns
Rise time	$t_r$		-	14	-	ns
Turn-off delay time	$t_{d(off)}$		-	185	-	ns
Fall time	$t_f$		-	15	-	ns
Turn-on energy	$E_{on}$		-	0.50	-	mJ
Turn-off energy	$E_{off}$		-	0.16	-	mJ
Total switching energy	$E_{ts}$		-	0.66	-	mJ
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 150^\circ\text{C}$ , $V_{CC} = 400\text{V}$ , $I_C = 5.0\text{A}$ , $V_{GE} = 0.0/15.0\text{V}$ , $R_{G(on)} = 15.0\Omega$ , $R_{G(off)} = 15.0\Omega$ , $L\sigma = 30\text{nH}$ , $C\sigma = 30\text{pF}$ $L\sigma$ , $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery.	-	18	-	ns
Rise time	$t_r$		-	5	-	ns
Turn-off delay time	$t_{d(off)}$		-	220	-	ns
Fall time	$t_f$		-	12	-	ns
Turn-on energy	$E_{on}$		-	0.14	-	mJ
Turn-off energy	$E_{off}$		-	0.05	-	mJ
Total switching energy	$E_{ts}$		-	0.19	-	mJ



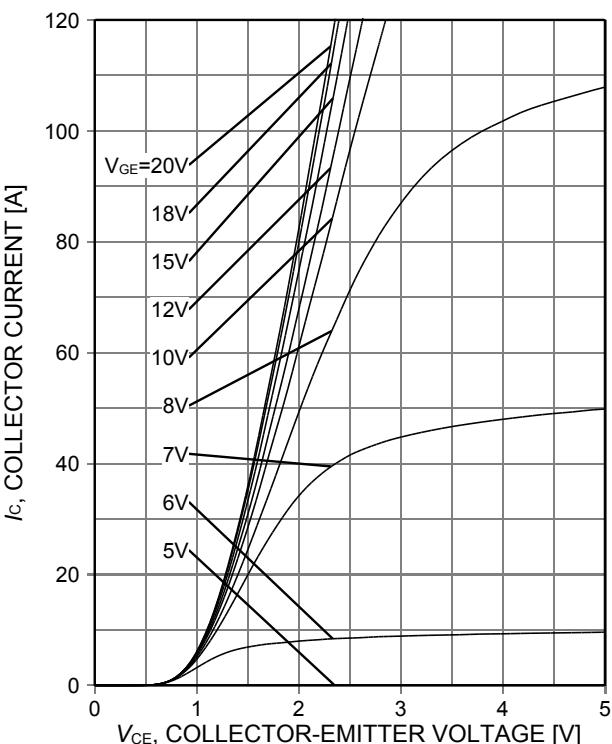
**Figure 1. Forward bias safe operating area**  
 $(D=0, T_c=25^\circ\text{C}, T_{vj}\leq 175^\circ\text{C}; V_{GE}=15\text{V}.$   
 Recommended use at  $V_{GE}\geq 7.5\text{V}$ )



**Figure 2. Power dissipation as a function of case temperature**  
 $(T_{vj}\leq 175^\circ\text{C})$



**Figure 3. Collector current as a function of case temperature**  
 $(V_{GE}\geq 15\text{V}, T_{vj}\leq 175^\circ\text{C})$



**Figure 4. Typical output characteristic**  
 $(T_{vj}=25^\circ\text{C})$

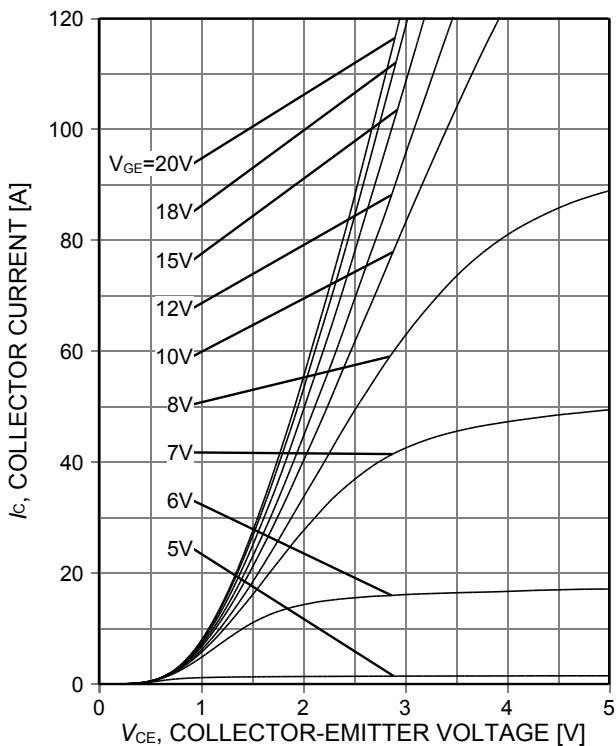


Figure 5. **Typical output characteristic**  
( $T_{vj}=150^{\circ}\text{C}$ )

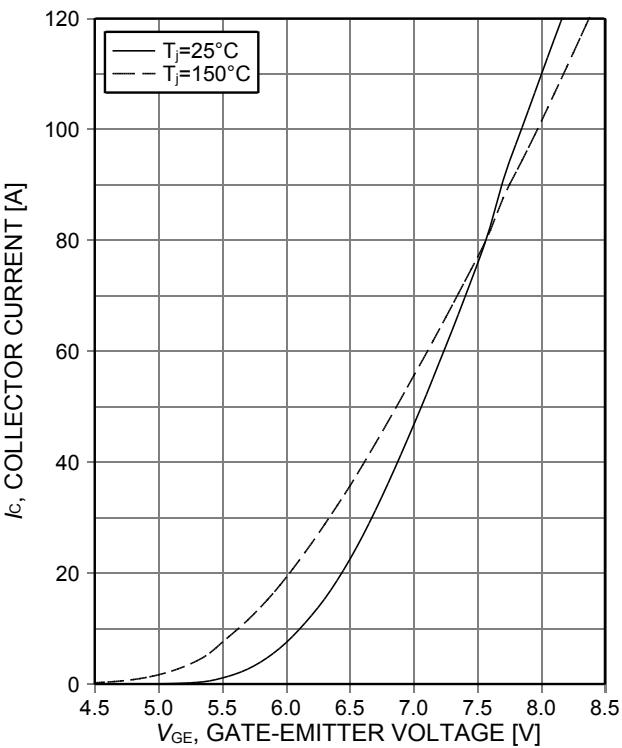


Figure 6. **Typical transfer characteristic**  
( $V_{CE}=20\text{V}$ )

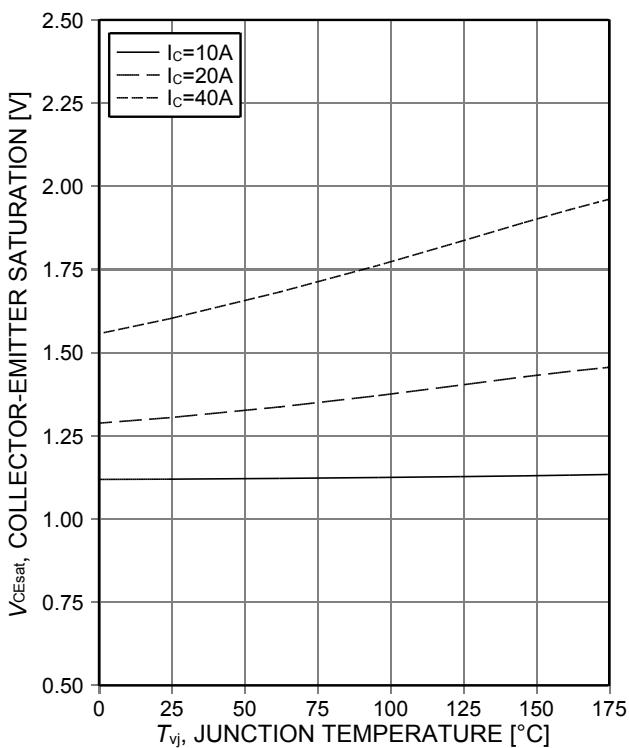


Figure 7. **Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE}=15\text{V}$ )

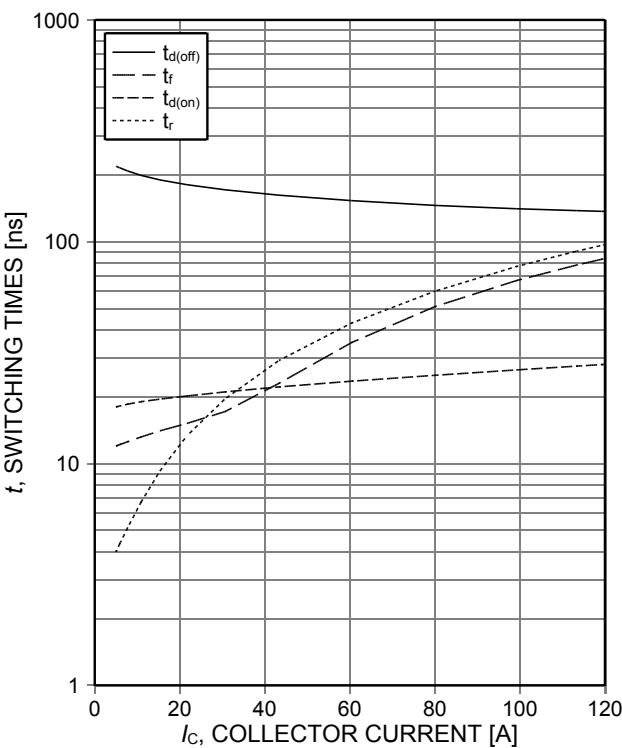
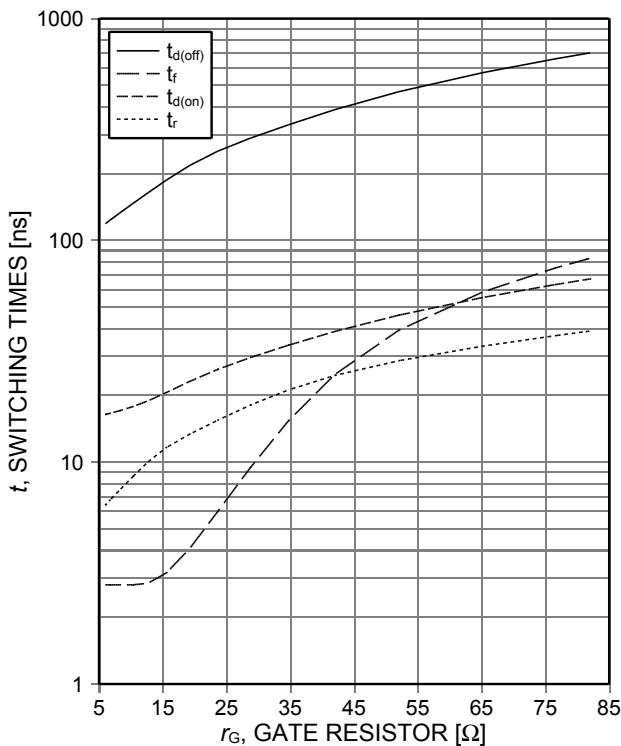
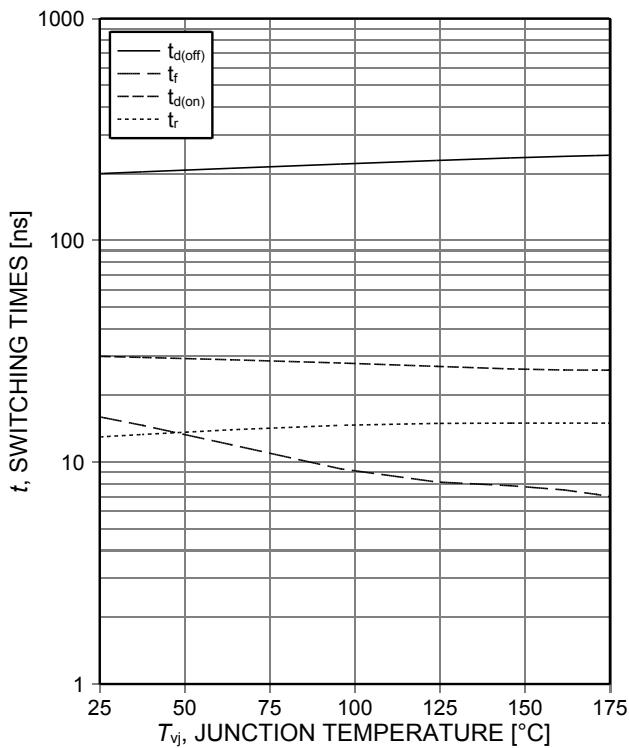


Figure 8. **Typical switching times as a function of collector current**  
(inductive load,  $T_{vj}=150^{\circ}\text{C}$ ,  $V_{CE}=400\text{V}$ ,  
 $V_{GE}=15/0\text{V}$ ,  $r_G=15\Omega$ , Dynamic test circuit in  
Figure E)



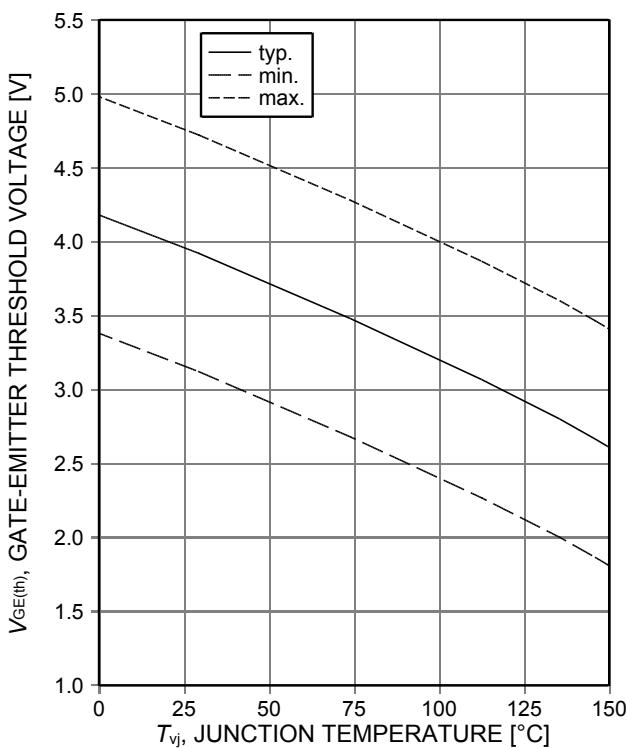
**Figure 9. Typical switching times as a function of gate resistor**

(inductive load,  $T_{vj}=150^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_c=20\text{A}$ , Dynamic test circuit in Figure E)

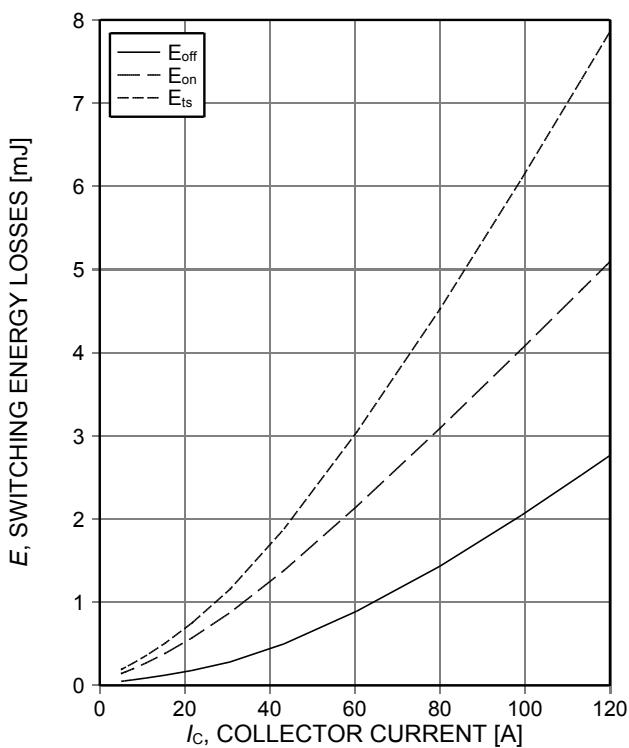


**Figure 10. Typical switching times as a function of junction temperature**

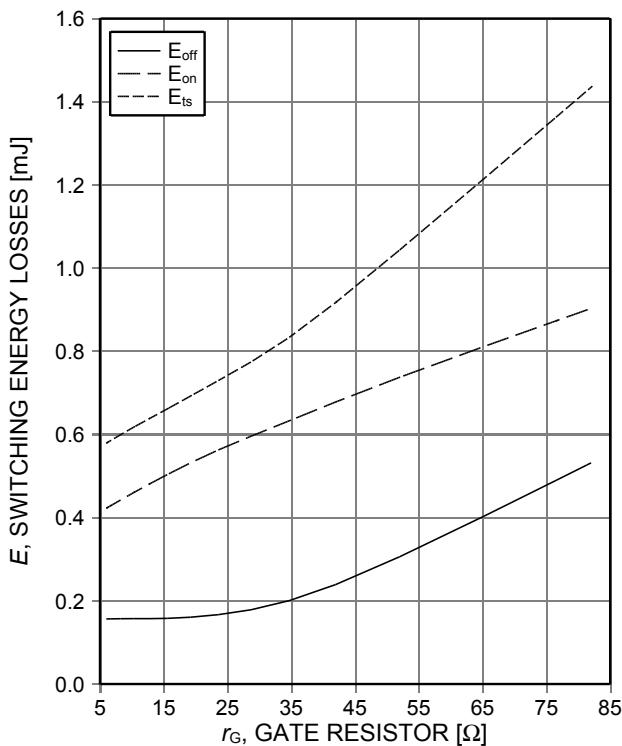
(inductive load,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $I_c=20\text{A}$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)



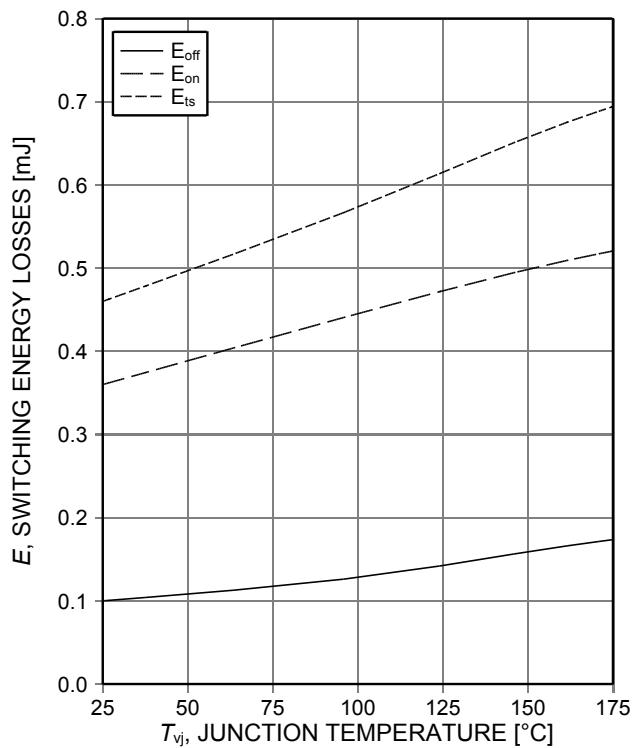
**Figure 11. Gate-emitter threshold voltage as a function of junction temperature**  
( $I_c=0.4\text{mA}$ )



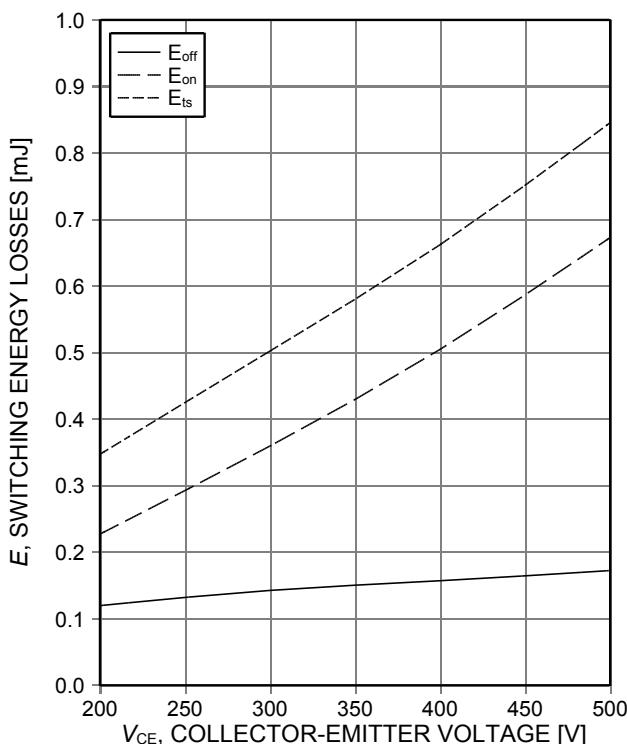
**Figure 12. Typical switching energy losses as a function of collector current**  
(inductive load,  $T_{vj}=150^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  $r_G=15\Omega$ , Dynamic test circuit in Figure E)



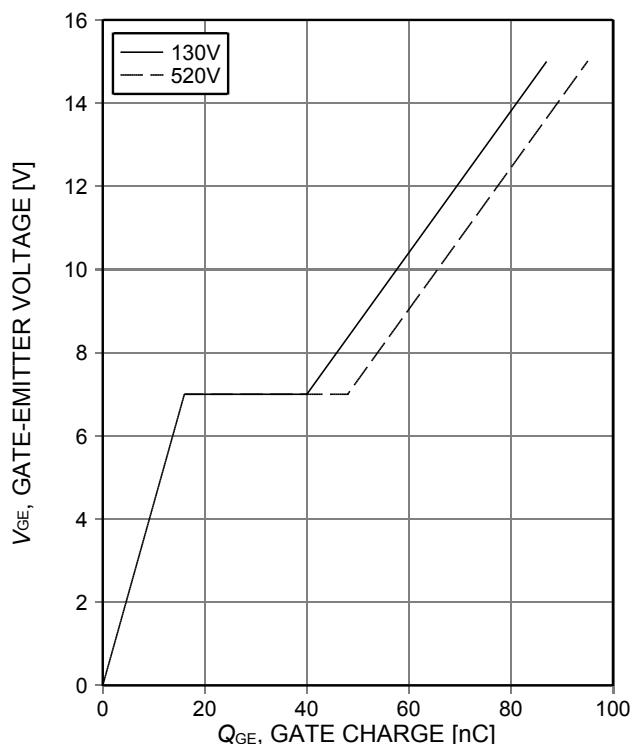
**Figure 13. Typical switching energy losses as a function of gate resistor**  
 (inductive load,  $T_{vj}=150^{\circ}\text{C}$ ,  $V_{CE}=400\text{V}$ ,  
 $V_{GE}=15/0\text{V}$ ,  $I_c=20\text{A}$ , Dynamic test circuit in  
 Figure E)



**Figure 14. Typical switching energy losses as a function of junction temperature**  
 (inductive load,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15/0\text{V}$ ,  
 $I_c=20\text{A}$ ,  $r_G=15\Omega$ , Dynamic test circuit in  
 Figure E)



**Figure 15. Typical switching energy losses as a function of collector-emitter voltage**  
 (inductive load,  $T_{vj}=150^{\circ}\text{C}$ ,  $V_{GE}=15/0\text{V}$ ,  
 $I_c=20\text{A}$ ,  $r_G=15\Omega$ , Dynamic test circuit in  
 Figure E)



**Figure 16. Typical gate charge**  
 $(I_c=40\text{A})$

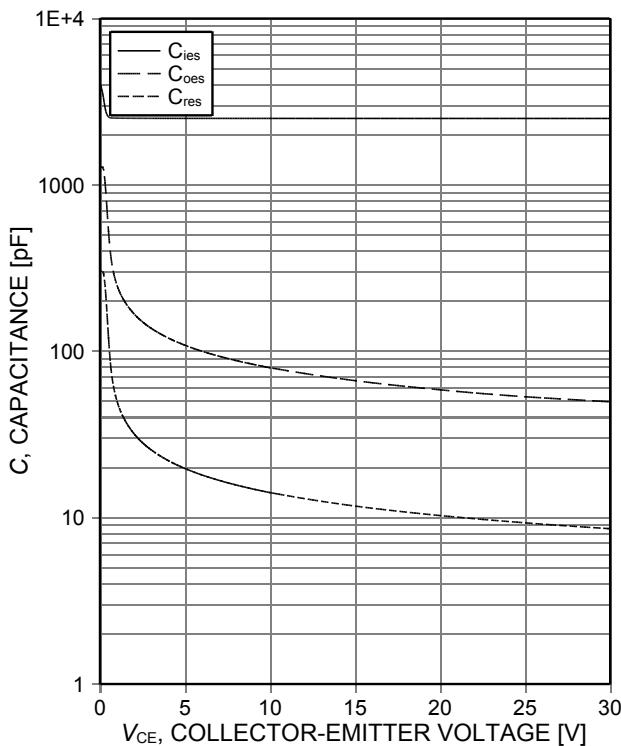


Figure 17. Typical capacitance as a function of collector-emitter voltage  
 $(V_{GE}=0V, f=1MHz)$

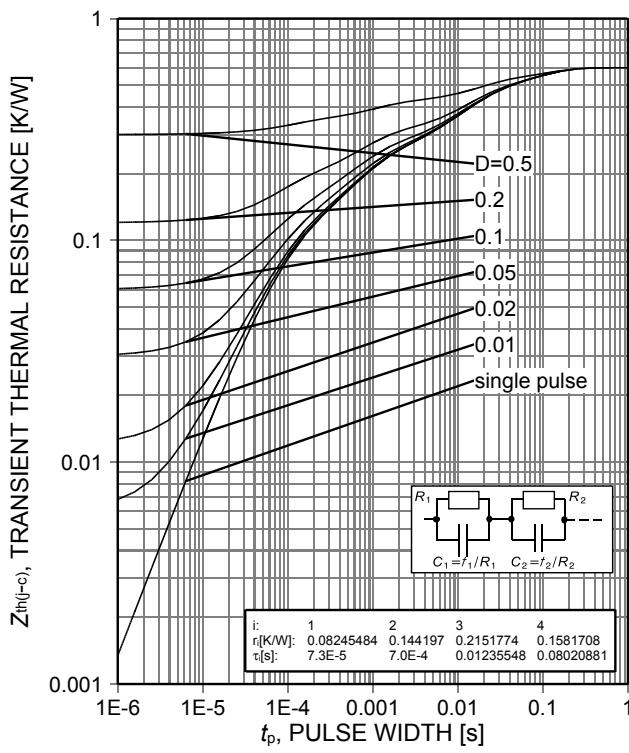
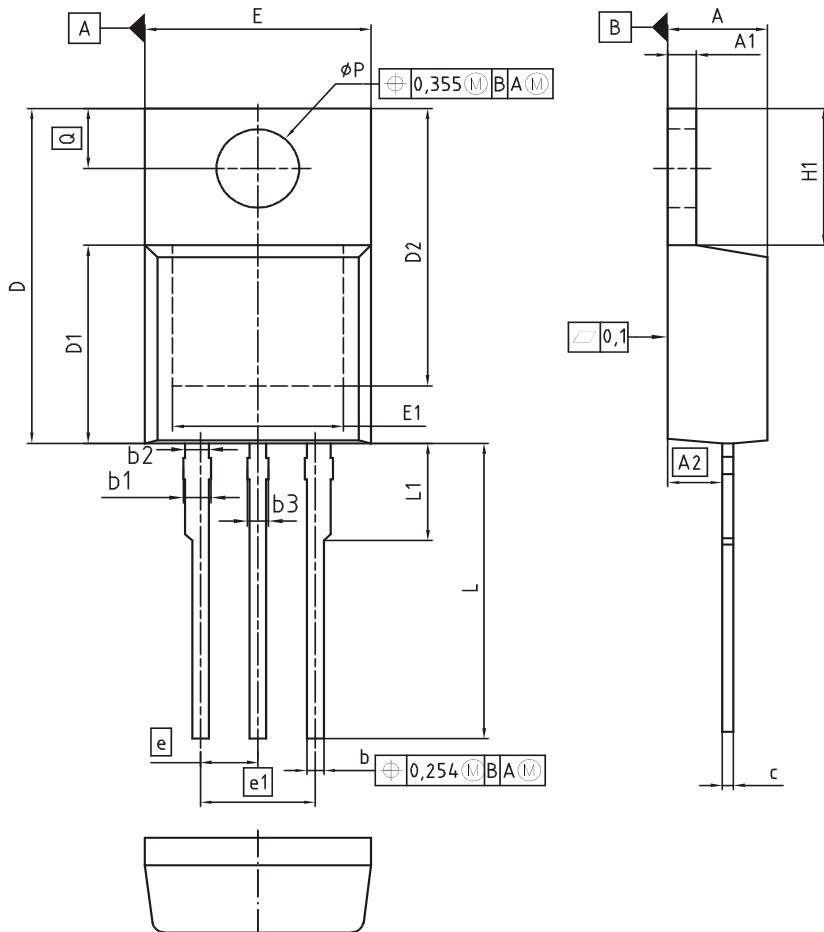


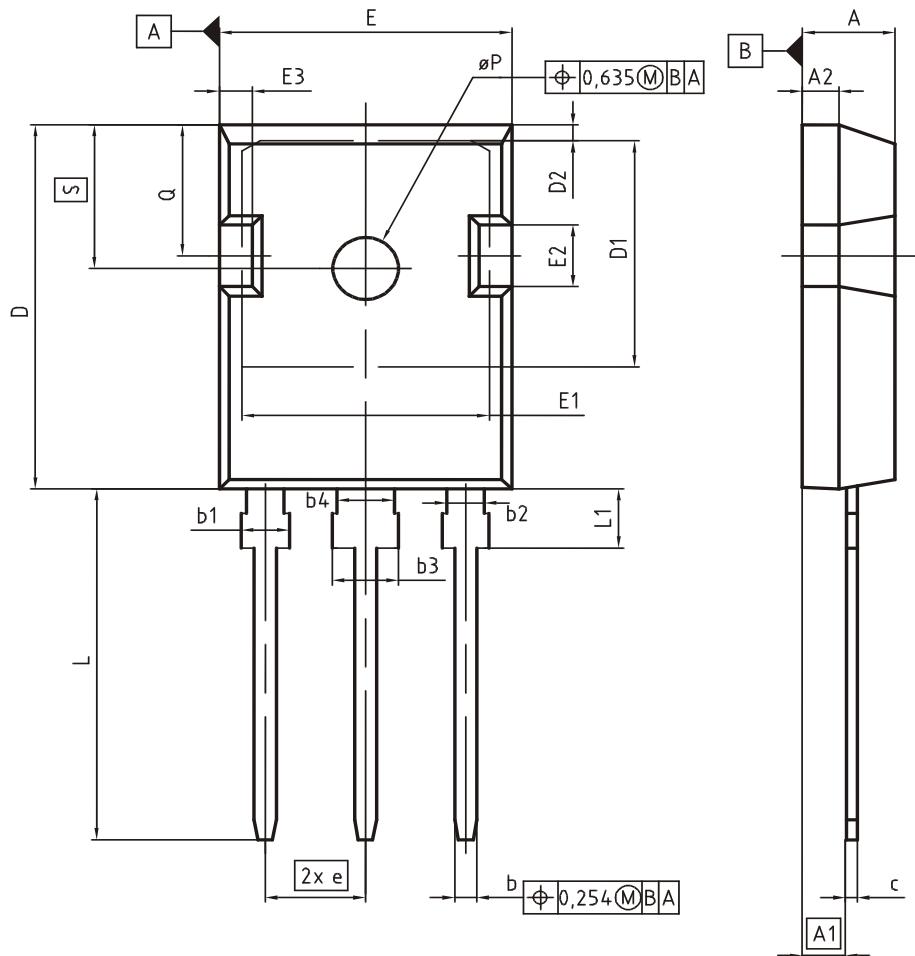
Figure 18. IGBT transient thermal resistance  
 $(D=t_p/T)$

**Package Drawing PG-T0220-3**


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
$\phi P$	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

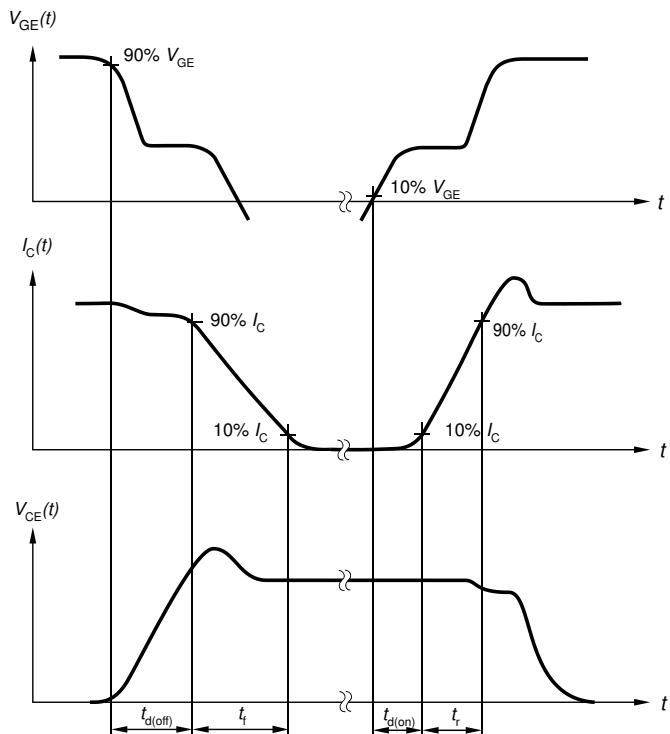
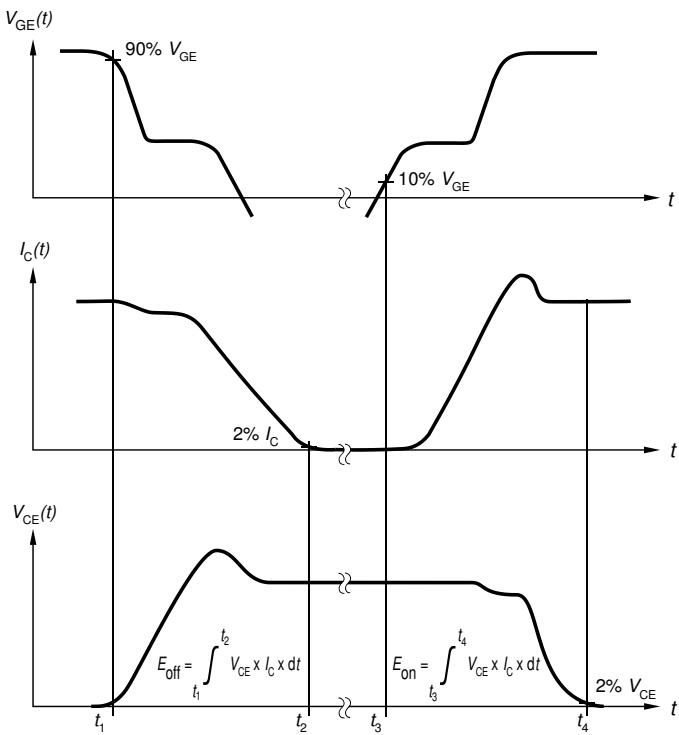
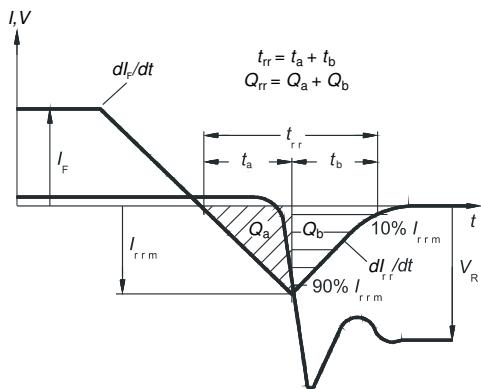
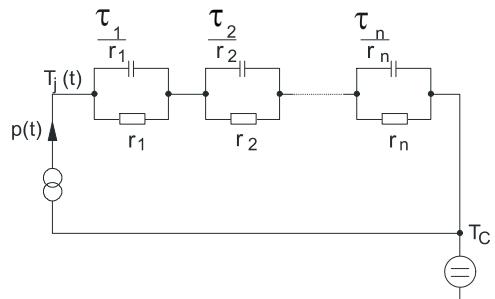
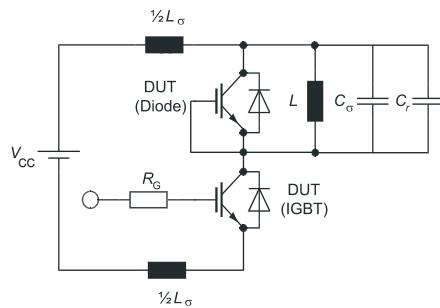
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SCALE	0 2.5 0 2.5 5mm
EUROPEAN PROJECTION	
ISSUE DATE	30-07-2009
REVISION	06

## Package Drawing PG-T0247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
ØP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO.	Z8B00003327
SCALE	0 0 5 5 7.5mm
EUROPEAN PROJECTION	
ISSUE DATE	09-07-2010
REVISION	05

**Testing Conditions**

**Figure A. Definition of switching times**

**Figure B. Definition of switching losses**

**Figure C. Definition of diode switching characteristics**

**Figure D. Thermal equivalent circuit**

**Figure E. Dynamic test circuit**  
Parasitic inductance  $L_\sigma$ ,  
parasitic capacitor  $C_\sigma$ ,  
relief capacitor  $C_r$ ,  
(only for ZVT switching)

## Revision History

IGP40N65F5, IGW40N65F5

### Revision: 2015-04-30, Rev. 2.1

#### Previous Revision

Revision	Date	Subjects (major changes since last revision)
1.1	2012-11-09	Preliminary data sheet
1.2	2013-12-16	New Marking Pattern
1.3	2014-12-04	Minor changes Fig.1 and Fig.14
2.1	2015-04-30	Final data sheet

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